

ABSTRACT

Provided is a bonding material that even in low-temperature bonding at 250°C or lower, enables bonding with sufficient bonding strength and with low tendency for unevenness between a sinter state of a central section and a sinter state of a pressed edge section at a pressure bonding surface. A sheet-shaped bonding material contains copper particles and a reductant that reduces the copper particles. The copper particles include fine copper particles having a mean particle diameter of 300 nm or less and optionally include coarse copper particles having a mean particle diameter of 3-11 μm . Content of the fine copper particles relative to the total content of the fine copper particles and the coarse copper particles is 50-100 mass%. The reductant is composed of triethanolamine, and content of the triethanolamine is 1.5-10.0 mass% relative to the total content of the fine copper particles and the coarse copper particles.